

One-stop PCBA	PCB+components sourcing+assembly+test+package
Assembly details	SMT and Thru-hole
Lead Time	Prototype: 7-15 work days. Batch order 20~25 work days usually
Testing on products	Flying Probe Test, X-ray Inspection, AOI Test, Functional test
PCB Solder Type	Water Soluble Solder Paste, RoHS lead free
Components details	Passive Down to 0201 size
	BGA and VFBGA
	Leadless Chip Carriers/CSP
	Double-sided SMT Assembly
	Fine Pitch to 0.8mils
	BGA Repair and Reball
	Part Removal and Replacement
Component package	Cut Tape,Tube,Reels,Loose Parts
PCB assembly process	Drilling---Exposure---Plating---Etaching & Stripping---Punching---Electrical Testing---SMT---Wave Soldering---AOI test---Assembling---ICT---Function Testing--Temperature & Humidity&Aging ect. Testing
PCB Max. size	DIP capacity
Min component size	201
Min.pin space of IC	0.3mm
Min. space of BGA	0.3mm
Max.precision of IC assembly	±0.03mm
SMT capacity	≥2 million points/day
DIP capacity	≥100k parts/day
SMT / DIP	1. Material Sourcing Service
	2. SMT assembly and Through hole components insertion
	3.100% AOI testing
	4. IC pre-programming / Burning on-line
	5.ICT testing
	6.Function testing as requested
	7.Complete Unit assembly (which including plastics, metal box, Coil, cable inside etc.)
	8.Conformal coating
	9.OEM/ODM also welcomed